## PATENT COOPERATION TREATY

## **PCT**

## INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

(Chapter II of the Patent Cooperation Treaty)

(PCT Article 36 and Rule 70)

Applicant's or agent's file reference P60206PCT	FOR FURTHER A	ACTION	See Form PCT/IPEA/416
International application No. PCT/EP2005/000698	International filing date 20.01.2005		Priority date (day/month/year) 29.01.2004
International Patent Classification H05K3/46, H05K3/18, H05	(IPC) or national classification and K3/10	IPC	
Applicant ATOTECH DEUTSCHLAN	D GMBH et al.		
Authority under Article 3	35 and transmitted to the applica	ant according to Article	is International Preliminary Examining 36.
	of a total of 5 sheets, including		
3. This report is also acco	mpanied by ANNEXES, compris	sing:	
a. 🛭 sent to the appli	cant and to the International Bu	reau) a total of 1 sheet	s, as tollows:
and <i>l</i> or shee <sup>:</sup> Administrati	ts containing rectifications authone lostructions).	orized by this Authority (	amended and are the basis of this report see Rule 70.16 and Section 607 of the
beyond the Supplement	disclosure in the international aptal Box.	pplication as filed, as inc	siders contain an amendment that goes dicated in item 4 of Box No. I and the
i anno liotino	rnational Bureau only) a total of and/or tables related thereto, in Sequence Listing (see Section i	i computer readable for	per of electronic carrier(s)) , containing a monly, as indicated in the Supplemental e Instructions).
4. This report contains inc	lications relating to the following	j items:	
	s of the opinion		·
Box No. II Prior			
		gard to novelty, inventive	e step and industrial applicability
	of unity of invention		
Mr. Boy No. V. Boss	the proof of the proof to prove the inventive etch or industrial		
	ain documents cited		
	ain defects in the international a		
☑ Box No. VIII Certa	ain observations on the internati	ional application	
Date of submission of the dema	nd	Date of completion of	this report
21.06.2005		16.02.2006	
Name and mailing address of the international preliminary examining authority:		Authorized Officer	Spatiaches Palaces . C.
European Patent	Office	Batev, P	
Fax: +49 89 239		Telephone No. +49 8	9 2399-7970

# 10/587691 IAP12 Rec'd PCT/PTO 27 JUL 2006

# INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

International application No. PCT/EP2005/000698

	Box No. I Basis of the rep	port		
1.	. With regard to the <b>language</b> , this report is based on the international application in the language in whic filed, unless otherwise indicated under this item.			
	☐ This report is based on t which is the language of	ranslations from the original language into the following language, a translation furnished for the purposes of:		
	Dublication of the interpretation	under Rules 12.3 and 23.1(b)) ernational application (under Rule 12.4) ary examination (under Rules 55.2 and/or 55.3)		
2.	have been furnished to the re	n regard to the <b>elements*</b> of the international application, this report is based on <i>(replacement sheets whice been furnished to the receiving Office in response to an invitation under Article 14 are referred to in this port as "originally filed" and are not annexed to this report):</i>		
	Description, Pages			
	1-37	as originally filed		
	Claims, Numbers			
	2-17	as originally filed		
	1	received on 21.06.2005 with letter of 17.06.2005		
	Drawings, Sheets			
	1/8-8/8	as originally filed		
	☐ a sequence listing and/o	or any related table(s) - see Supplemental Box Relating to Sequence Listing		
3.	.   The amendments have	The amendments have resulted in the cancellation of:		
	the description, pages			
	<ul><li>☐ the claims, Nos.</li><li>☐ the drawings, sheets</li></ul>	dias		
	☐ the sequence listing	(specify):		
	☐ any table(s) related t	o sequence listing (specify):		
4.	☐ This report has been established as if (some of) the amendments annexed to this report and listed below had not been made, since they have been considered to go beyond the disclosure as filed, as indicated in the Supplemental Box (Rule 70.2(c)).			
	the description, pages			
	<ul><li>the claims, Nos.</li><li>the drawings, sheets</li></ul>	offigs		
	☐ the sequence listing	(specify):		
	☐ any table(s) related t	to sequence listing (specify):		
		some or all of these sheets may be marked "superseded "		

International application No. PCT/EP2005/000698

Box No. V Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

1. Statement

Novelty (N)

Yes: Claims

1-17

No: Claims

none 1-17

none

Inventive step (IS)

Yes: Claims No: Claims

٥.

Industrial applicability (IA)

Yes: Claims

Claims

1-17

No:

none

2. Citations and explanations (Rule 70.7):

see separate sheet

## Box No. VII Certain defects in the international application

The following defects in the form or contents of the international application have been noted:

see separate sheet

## Box No. VIII Certain observations on the international application

The following observations on the clarity of the claims, description, and drawings or on the question whether the claims are fully supported by the description, are made:

see separate sheet

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#### Re Item V

Reasoned statement with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

Reference is made to the following document:

- D1: US 2002/129972 A1 (KONRAD JOHN JOSEPH ET AL) 19 September 2002 (2002-09-19)
- 1. Document D1 discloses (paragraphs 18 39; figs. 1a 1d) a method of manufacturing a circuit carrier, the method comprising the following steps:
  - a) providing a substrate 1;
  - b) coating the substrate on one side thereof with a dielectric 2;
- c) structuring the dielectric for producing trenches and vias 3 therein, using laser ablation:
  - d) depositing a primer layer 4 into the produced trenches and vias only;
- e) depositing a metal layer 5 onto the primer layer, with the trenches and vias being completely filled with metal for forming conductor structures therein.

Thus, the subject matter of claim 1 differs from this known method at least in that

- i) in step a) a printed circuit board is provided instead of a substrate; and
- ii) the trenches produced in step c) do not extend completely through the dielectric.

Consequently, the subject matter of claim 1 is new (Article 33(2) PCT).

2. Even if the skilled person interchanged the substrate in step a) of the known method with a circuit board, e.g. a single sided board, and used the side free of conductors as an equivalent to using a substrate, he would not arrive at the subject matter of claim 1 as he has no incitement to provide trenches which do not extend completely through the dielectric.

None of the other cited documents, which reflect the technological background, discloses or gives an incitement to the specific solution proposed in claim 1.

In view of the available prior art, the subject matter of claim 1 appears, therefore, to involve an inventive step (Article 33(3) PCT).

3. Claims 2 - 16 which define preferred embodiments of the invention are dependent on

claim 1 and as such also meet the requirements of the PCT in respect of novelty and inventive step.

Independent claim 17 is directed to an use of the method defined in claim 1. Its subject matter is therefore also new and inventive.

#### Re Item VII

### Certain defects in the international application

1. Contrary to the requirements of Rule 5.1(a)(ii) PCT, the relevant background art disclosed in the document D1 is not mentioned in the description, nor is this document identified therein (see also the Guidelines, paragraph 4.05).

#### Re Item VIII

### Certain observations on the international application

1. The last paragraph on page 36 of the description implies that the subject matter for which protection is sought may be different to that defined by the claims. This results in lack of clarity of the claims (Article 6 PCT) when the description is used to interpret them (see the Guidelines, paragraph 5.30).

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PCT/EP2005/000698 Atotech Deutschland GmbH 17.06.2005

**EPO - DG 1** 

2 1. 06. 2005



#### Claims:

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- A method of manufacturing a circuit carrier, said method comprising the following method steps:
  - a) Providing a printed circuit board;
  - b) Coating the circuit board on at least one side thereof with a dielectric;
  - c) Structuring the dielectric for producing trenches and vias therein using laser ablation, the trenches not extending completely through the dielectric;
  - Depositing a primer layer onto the entire surface of the dielectric or depositing the primer layer into the produced trenches and vias only;
  - e) Depositing a metal layer onto the primer layer, with the trenches and vias being completely filled with metal for forming conductor structures therein; and
  - f) Removing the metal layer and the primer layer, except for in the trenches and vias, to expose the dielectric if the primer layer has been deposited onto the entire surface in method step d).

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